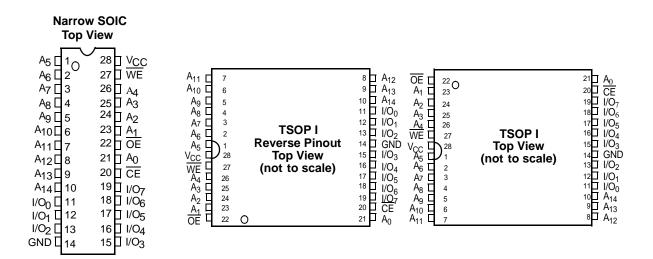


Product Portfolio

						Power Dissipation			
		Va	_{CC} Range ((V)	Speed	Operating	I, I _{CC} (mA)	Standby,	I _{SB2} (μΑ)
Product	Range	Min.	Typ. ^[2]	Max.	(ns)	Typ. ^[2]	Max.	Typ. ^[2]	Max.
CY62256VLL	Com'l/Ind'l	2.7	3.0	3.6	70	11	30	0.1	5
	Automotive								130

Pin Configurations



Pin Definitions

Pin Number	Туре	Description
1–10, 21, 23–26	Input	A ₀ -A ₁₄ . Address Inputs
11–13, 15–19	Input/Output	I/O ₀ -I/O ₇ . Data lines. Used as input or output lines depending on operation
27	Input/Control	WE. When selected LOW, a WRITE is conducted. When selected HIGH, a READ is conducted
20	Input/Control	CE. When LOW, selects the chip. When HIGH, deselects the chip
22	Input/Control	OE . Output Enable. Controls the direction of the I/O pins. When LOW, the I/O pins behave as outputs. When deasserted HIGH, I/O pins are Tri-stated, and act as input data pins
14	Ground	GND. Ground for the device
28	Power Supply	V _{CC} . Power supply for the device

Note:

2. Typical values are included for reference only and are not guaranteed or tested. Typical values are measured at $V_{CC} = V_{CC(typ.)}$, $T_A = 25^{\circ}C$, and $t_{AA} = 70$ ns.



CY62256V

Maximum Ratings

(Above which the useful life may be impaired. For user guide-lines, not tested.) $\label{eq:stable}$

Storage Temperature65°C to +150°C	;
Ambient Temperature with Power Applied55°C to +125°C	;
Supply Voltage to Ground Potential (Pin 28 to Pin 14)0.5V to +4.6V	,
DC Voltage Applied to Outputs in High-Z State ^[3] 0.5V to V_{CC} + 0.5V DC Input Voltage ^[3] 0.5V to V_{CC} + 0.5V	

Output Current into Outputs (LOW)	. 20 mA
Static Discharge Voltage>	2001V

(per MIL-STD-883, Method 3015)	

Latch-up Current...... > 200 mA

Operating Range

Device	Range	Ambient Temperature (T _A) ^[4]	V _{cc}
CY62256V	Commercial	0°C to +70°C	2.7V to 3.6V
	Industrial	–40°C to +85°C	
	Automotive	–40°C to +125°C	

Electrical Characteristics Over the Operating Range

				CY62256V-70			
Parameter	Description	Test Conditions		Min.	Typ. ^[2]	Max.	Unit
V _{OH}	Output HIGH Voltage	I _{OH} = -1.0 mA	$V_{CC} = 2.7V$	2.4			V
V _{OL}	Output LOW Voltage	I _{OL} = 2.1 mA	V _{CC} = 2.7V			0.4	V
V _{IH}	Input HIGH Voltage			2.2		V _{CC} +0.3V	V
V _{IL}	Input LOW Voltage			-0.5		0.8	V
I _{IX}	Input Leakage Current	$GND \le V_{IN} \le V_{CC}$	Com'l, Ind'l	-1		+1	μA
			Automotive	-10		+10	μA
I _{OZ}	Output Leakage Current	$GND \le V_{IN} \le V_{CC}$, Output Disabled	Com'l, Ind'l	-1		+1	μA
			Automotive	-10		+10	μA
I _{CC}	V _{CC} Operating Supply Current	$V_{CC} = 3.6V$, $I_{OUT} = 0$ mA, f = f _{Max} = 1/t _{RC}	All ranges		11	30	mA
I _{SB1}	Automatic CE Power-down Current— TTL Inputs	$ \begin{array}{l} V_{CC} = 3.6 \text{V}, \overline{CE} \geq \text{V}_{\text{IH}}, \\ \text{V}_{\text{IN}} \geq \text{V}_{\text{IH}} \text{ or } \text{V}_{\text{IN}} \leq \text{V}_{\text{IL}}, \text{ f} = \text{f}_{\text{Max}} \end{array} $	All ranges		100	300	μA
I _{SB2}	Automatic CE Power-down	$V_{CC} = 3.6V, \overline{CE} \ge V_{CC} - 0.3V$	Com'l		0.1	5	μA
	Current— CMOS Inputs	$V_{IN} \ge V_{CC} - 0.3V \text{ or } V_{IN} \le 0.3V, f = 0$	Ind'l		0.1	10	
			Automotive		0.1	130	

Notes:

3. V_{IL} (min.) = -2.0V for pulse durations of less than 20 ns. 4. T_{A} is the "Instant-On" case temperature.



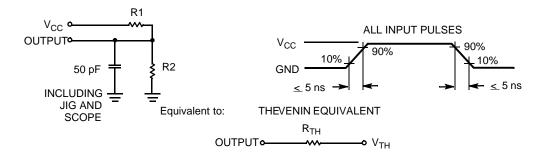
Capacitance^[5]

Parameter	Description	Test Conditions	Max.	Unit
C _{IN}	Input Capacitance	$T_A = 25^{\circ}C$, f = 1 MHz, $V_{CC} = V_{CC(typ.)}$	6	pF
C _{OUT}	Output Capacitance		8	pF

Thermal Resistance

Parameter	Description	Test Conditions	SOIC	TSOPI	RTSOPI	Unit
Θ_{JA}	Thermal Resistance (Junction to Ambient) ^[6]	Still Air, soldered on a 3 × 4.5 inch, 2-layer printed circuit board	68.45	87.62	87.62	°C/W
Θ ^{JC}	Thermal Resistance (Junction to Case) ^[5]		26.94	23.73	23.73	°C/W

AC Test Loads and Waveforms

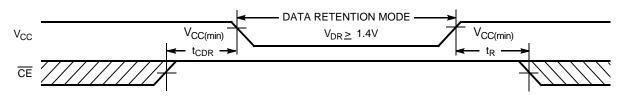


Parameter	3.3V	Units
R1	1100	Ohms
R2	1500	Ohms
R _{TH}	645	Ohms
V _{TH}	1.750	Volts

Data Retention Characteristics (Over the Operating Range)

Parameter	Description	Conditions ^[6]		Min.	Typ. ^[2]	Max.	Unit
V _{DR}	V _{CC} for Data Retention			1.4			V
I _{CCDR}	Data Retention Current	$V_{CC} = 1.4V, \overline{CE} \ge V_{CC} - 0.3V,$ $V_{IN} \ge V_{CC} - 0.3V \text{ or } V_{IN} \le 0.3V$	Com'l		0.1	3	μA
		$V_{IN} \ge V_{CC} - 0.3V \text{ or } V_{IN} \le 0.3V$	Ind'l		0.1	6	
			Auto		0.1	50	
t _{CDR} ^[6]	Chip Deselect to Data Retention Time			0			ns
t _R ^[6]	Operation Recovery Time			t _{RC}			ns

Data Retention Waveform



Notes:

5. Tested initially and after any design or process changes that may affect these parameters.

6. No input may exceed V_{CC} + 0.3V.



Switching Characteristics Over the Operating Range^[7]

		CY622	256V-70	
Parameter	Description	Min.	Max.	Unit
Read Cycle				
t _{RC}	Read Cycle Time	70		ns
t _{AA}	Address to Data Valid		70	ns
t _{OHA}	Data Hold from Address Change	10		ns
t _{ACE}	CE LOW to Data Valid		70	ns
t _{DOE}	OE LOW to Data Valid		35	ns
t _{LZOE}	OE LOW to Low-Z ^[8]	5		ns
t _{HZOE}	OE HIGH to High-Z ^[8, 9]		25	ns
t _{LZCE}	CE LOW to Low-Z ^[8]	10		ns
t _{HZCE}	CE HIGH to High-Z ^[8, 9]		25	ns
t _{PU}	CE LOW to Power-up	0		ns
t _{PD}	CE HIGH to Power-down		70	ns
Write Cycle ^[10, 11]	·	·		
t _{WC}	Write Cycle Time	70		ns
t _{SCE}	CE LOW to Write End	60		ns
t _{AW}	Address Set-up to Write End	60		ns
t _{HA}	Address Hold from Write End	0		ns
t _{SA}	Address Set-up to Write Start	0		ns
t _{PWE}	WE Pulse Width	50		ns
t _{SD}	Data Set-up to Write End	30		ns
t _{HD}	Data Hold from Write End	0		ns
t _{HZWE}	WE LOW to High-Z ^[8, 9]		25	ns
t _{LZWE}	WE HIGH to Low-Z ^[8]	10		ns

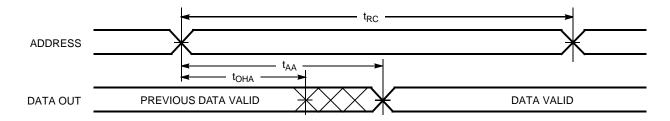
Notes:

Notes:
7. Test conditions assume signal transition time of 5 ns or less timing reference levels of V_{CC}/2, input pulse levels of 0 to V_{CC}, and output loading of the specified I_{OL}/I_{OH} and 50 pF load capacitance.
8. At any given temperature and voltage condition, t_{HZCE} is less than t_{LZCE}, t_{HZOE} is less than t_{LZOE}, and t_{HZWE} is less than t_{LZWE} for any given device.
9. t_{HZOE}, t_{HZCE}, and t_{HZWE} are specified with C_L = 5 pF as in (b) of A<u>C</u> Test Loads. <u>Transition</u> is measured ± 200 mV from steady-state voltage.
10. The internal write time of the memory is defined by the overlap of CE LOW and WE LOW. Both signals must be LOW to initiate a write and either signal can terminate a write by going HIGH. The data input set-up and hold timing should be referenced to the rising edge of the signal that terminates the write.
11. The minimum write cycle time for write cycle #3 (WE controlled, OE LOW) is the sum of t_{HZWE} and t_{SD}.

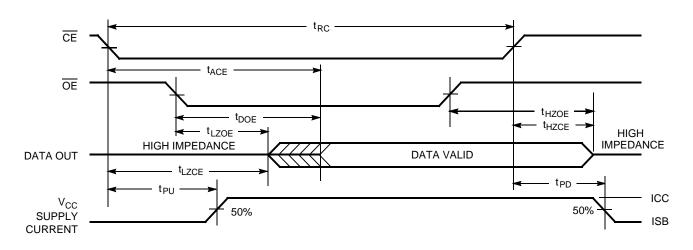


Switching Waveforms

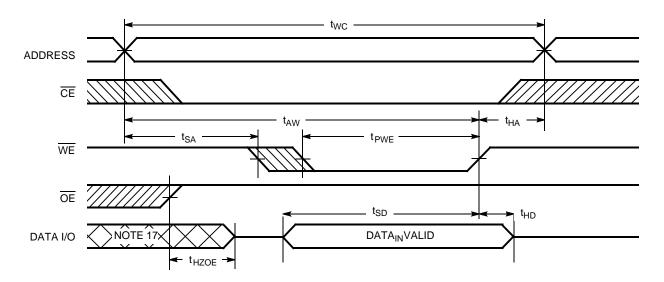
Read Cycle No. 1 (Address Transition Controlled)^[12, 13]



Read Cycle No. 2 (OE Controlled)^[13, 14]



Write Cycle No. 1 (WE Controlled)^[10, 15, 16]



Notes:

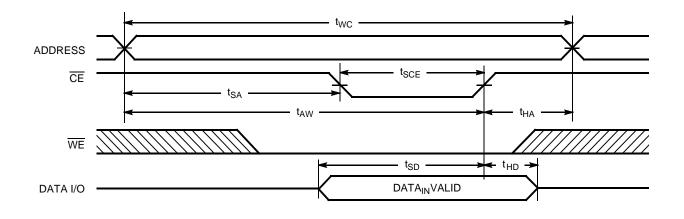
- 12. Device is continuously selected. \overline{OE} , $\overline{CE} = V_{IL}$. 13. WE is HIGH for read cycle.
- 14. Address valid prior to or coincident with CE transition LOW.
- 15. Data I/O is high impedance if $\overline{OE} = V_{|\mathbf{H}|}$. 16. If \overline{CE} goes HIGH simultaneously with WE HIGH, the output remains in a high-impedance state.
- 17. During this period, the I/Os are in output state and input signals should not be applied.



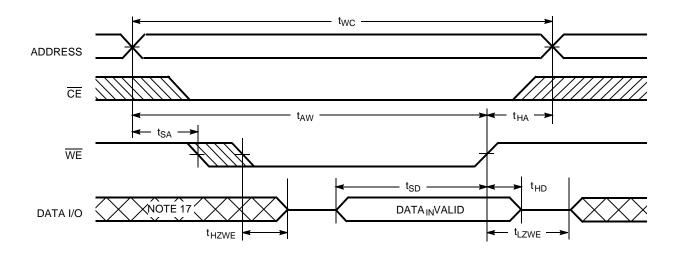
CY62256V

Switching Waveforms (continued)

Write Cycle No. 2 (CE Controlled)^[10, 15, 16]

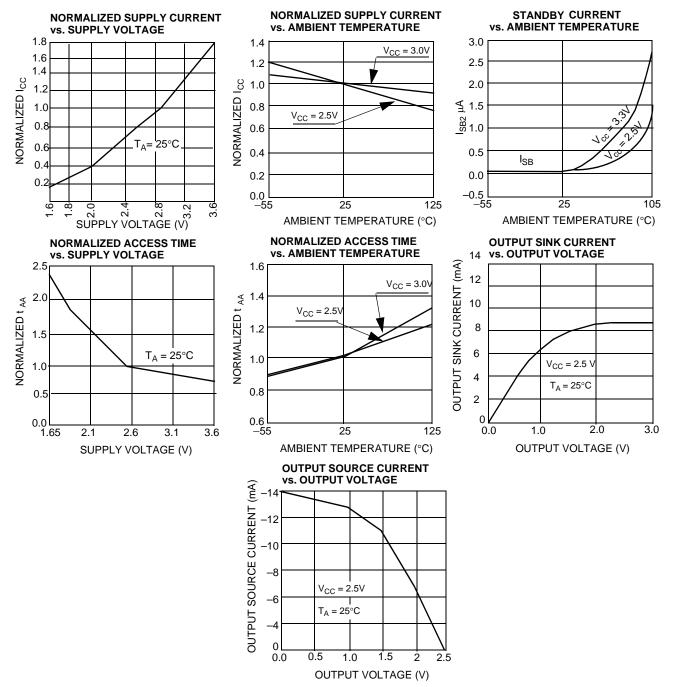


Write Cycle No. 3 ($\overline{\text{WE}}$ Controlled, $\overline{\text{OE}}$ LOW)^[11, 16]



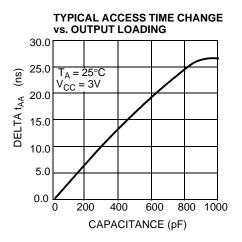


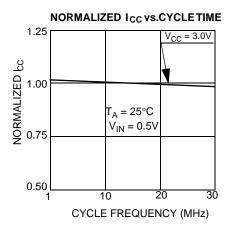
Typical DC and AC Characteristics





Typical DC and AC Characteristics (continued)





Truth Table

CE	WE	OE	Inputs/Outputs	Mode	Power
Н	Х	Х	High-Z	Deselect/Power-down	Standby (I _{SB})
L	Н	L	Data Out	Read	Active (I _{CC})
L	L	Х	Data In	Write	Active (I _{CC})
L	Н	Н	High-Z	Deselect, Output Disabled	Active (I _{CC})

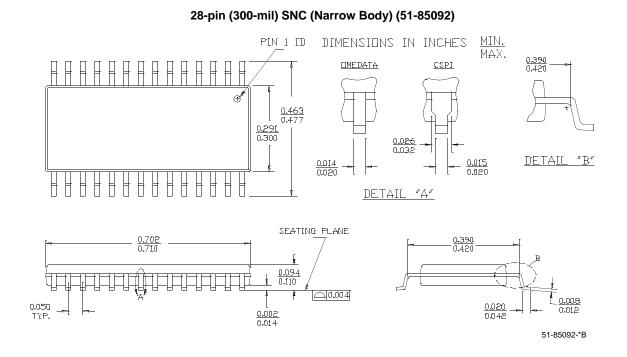
Ordering Information

Speed (ns)	Ordering Code	Package Diagram	Package Type	Operating Range
70	CY62256VLL-70SNC	51-85092	28-pin (300-mil Narrow Body) SNC	Commercial
	CY62256VLL-70SNXC		28-pin (300-mil Narrow Body) SNC (Pb-Free)	
	CY62256VLL-70ZC	51-85071	28-pin TSOP I	
	CY62256VLL-70ZXC		28-pin TSOP I (Pb-Free)	
	CY62256VLL-70SNXI	51-85092	28-pin (300-mil Narrow Body) SNC (Pb-Free)	Industrial
	CY62256VLL-70ZI	51-85071	28-pin TSOP I	
	CY62256VLL-70ZXI		28-pin TSOP I (Pb-Free)	
	CY62256VLL-70ZRI	51-85074	28-pin Reverse TSOP I	
	CY62256VLL-70ZRXI		28-pin Reverse TSOP I (Pb-Free)	
	CY62256VLL-70SNE	51-85092	28-pin (300-mil Narrow Body) SNC	Automotive
	CY62256VLL-70SNXE		28-pin (300-mil Narrow Body) SNC (Pb-Free)	
	CY62256VLL-70ZE	51-85071	28-pin TSOP I	
	CY62256VLL-70ZXE		28-pin TSOP I (Pb-Free)	
	CY62256VLL-70ZRE	51-85074	28-pin Reverse TSOP I	
	CY62256VLL-70ZRXE		28-pin Reverse TSOP I (Pb-Free)	

Please contact your local Cypress sales representative for availability of these parts

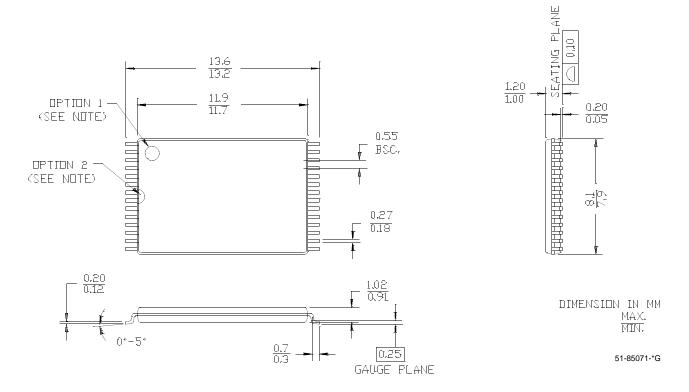


Package Diagrams



28-pin Thin Small Outline Package Type 1 (8 × 13.4 mm) (51-85071)

NATE: DRIENTATION I,D MAY BE LOCATED EITHER AS SHOWN IN APTION 1 OR APTION 2

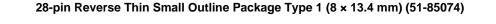


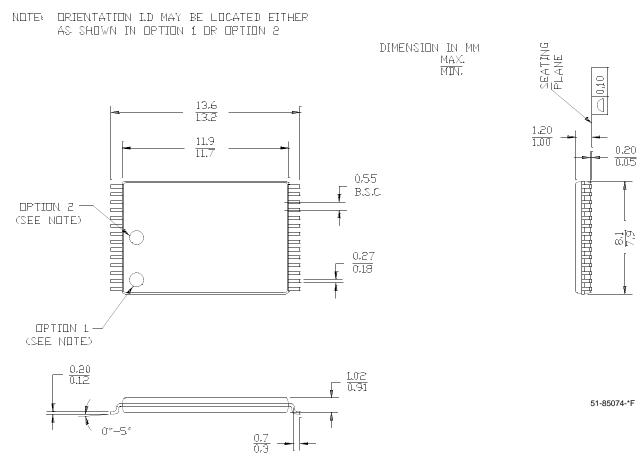
Document #: 38-05057 Rev. *F

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Package Diagrams (continued)





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Document History Page

REV.	ECN NO.	Issue Date	Orig. of Change	Description of Change
**	107248	09/10/01	SZV	Changed from spec number: 38-00519 to 38-05057
*A	111445	11/01/01	MGN	Removed obsolete parts. Change to standard format
*B	115229	05/23/02	GBI	Changed SN package diagram
*C	116507	09/04/02	GBI	Added footnote 1 Clarified I_{CC} spec for $V_{CC(typ)} = 2.5V$
*D	239134	See ECN	AJU	Added Automotive product information
*E	344595	See ECN	SYT	Added Pb-Free packages on page# 10
*F	493277	See ECN	VKN	Changed address of Cypress Semiconductor Corporation on Page# 1 from "3901 North First Street" to "198 Champion Court" Removed part # CY62256V25LL from the product offering Updated Ordering Information Table